

L Number	Hits	Search Text	DB	Time stamp
1	67935	dic\$3	USPAT; US-PGPUB; JPO	2003/10/02 16:49
2	1757487	groove\$1 or channel\$3 or recess\$2	USPAT; US-PGPUB; JPO	2003/10/02 16:49
3	2540235	depress\$3 or hole\$1 or opening\$1	USPAT; US-PGPUB; JPO	2003/10/02 16:50
4	47495	trench\$2	USPAT; US-PGPUB; JPO	2003/10/02 16:50
5	170059	encapsulat\$3 or passivat\$4	USPAT; US-PGPUB; JPO	2003/10/02 16:50
6	34362	bond\$3 near2 pad\$1	USPAT; US-PGPUB; JPO	2003/10/02 16:51
7	4161	dic\$3 with ((groove\$1 or channel\$3 or recess\$2) or (depress\$3 or hole\$1 or opening\$1) or trench\$2)	USPAT; US-PGPUB; JPO	2003/10/02 16:52
8	25389	solder\$3 near3 (bump\$1 or ball\$1 or pattern\$1)	USPAT; US-PGPUB; JPO	2003/10/02 16:52
9	4073	((bond\$3 near2 pad\$1) same (solder\$3 near3 (bump\$1 or ball\$1 or pattern\$1)))	USPAT; US-PGPUB; JPO	2003/10/02 16:52
10	121	((encapsulat\$3 or passivat\$4) and (dic\$3 with ((groove\$1 or channel\$3 or recess\$2) or (depress\$3 or hole\$1 or opening\$1) or trench\$2)) and ((bond\$3 near2 pad\$1) same (solder\$3 near3 (bump\$1 or ball\$1 or pattern\$1))))	USPAT; US-PGPUB; JPO	2003/10/02 16:52